

## Product Change Notice

Issue Date: March 11, 2020

**Change Type:**

Add Assembly Production Site – ASE Taiwan

**Parts Affected:**

BCM59202AKFSBG  
BCM59850A0KFSBG  
BCM81328A0KFSBG  
BCM81329A0KFSBG  
BCM81330A0KFSBG  
BCM82040B0KFEBG  
BCM82070BKFSBG  
BCM82072BKFSBG  
BCM82073BIFSBG  
BCM82073BKFSBG  
BCM82209BIFSBG  
BCM82209BKFSBG  
BCM82212BIFSBG  
BCM82322B1KFSBG  
BCM82332AKFSBG  
BCM82380BKFSBG  
BCM82381BIFSBG  
BCM82381BKFSBG  
BCM82383BKFSBG  
BCM82385BKFSBG  
BCM82391AKFSBG  
BCM82396AIFSBG  
BCM82396AKFSBG  
BCM82397AIFSBG  
BCM82397AKFSBG  
BCM82398AIFSBG  
BCM82398AKFSBG  
BCM82399AIFSBG  
BCM82399AKFSBG  
BCM82755AIFSBG  
BCM82756AIFSBG  
BCM82756AKFSBG  
BCM82757AIFSBG  
BCM82757AKFSBG  
BCM82759A0IFSBG  
BCM82759AKFSBG  
BCM82793AKFSBG  
BCM82980AKFSBG

**Description and Extent of Change:**

Add ASE Taiwan as the assembly supplier for the above device

**Reasons for Change:**

Supply Chain manufacturing flexibility and capacity

**Effect of Change on Fit, Form, Function, Quality, or Reliability:**

There will be no change in fit, form, function, quality or reliability

**Effective Date of Change:**

June 18, 2020

**Software / Firmware Update:**

There will be no changes in Software / Firmware.

**Qualification Data:**

Package Qualification Reference#: 004487  
Fab Technology: 28nm  
Package Type: FCBGA+HS  
Package Size: 35 x 35  
Lead Count: 1413

Stress Test	Condition	Read points	Sample Size	Requirements	Results (# fail/ss)
		Cycles / Hrs.			
Precondition	MSL3 JESD22-A113E		154 units	0 failures	0 / 154
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	77 units	0 failures	0 / 77
uHast	130°C/85%RH JEDEC Std. 22-A102-C	96hrs	77 units	0 failures	0 / 77
HTSL	TA=150°C	1000hrs	77 units	0 failures	0 / 77

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Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.